

SOT589-1

plastic ball grid array package; 553 balls; body 37.5 x 37.5 x 1.75 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA553
Package type industry code	BGA553
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	25-11-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	37.3	-	37.5	37.7	mm
E	package width	37.3	-	37.5	37.7	mm
A	seated height	[tbd]	-	2.55	2.55	mm
A ₂	package height	1.6	-	1.75	1.85	mm
n ₂	actual quantity of termination	-	-	553	-	



2. Package outline

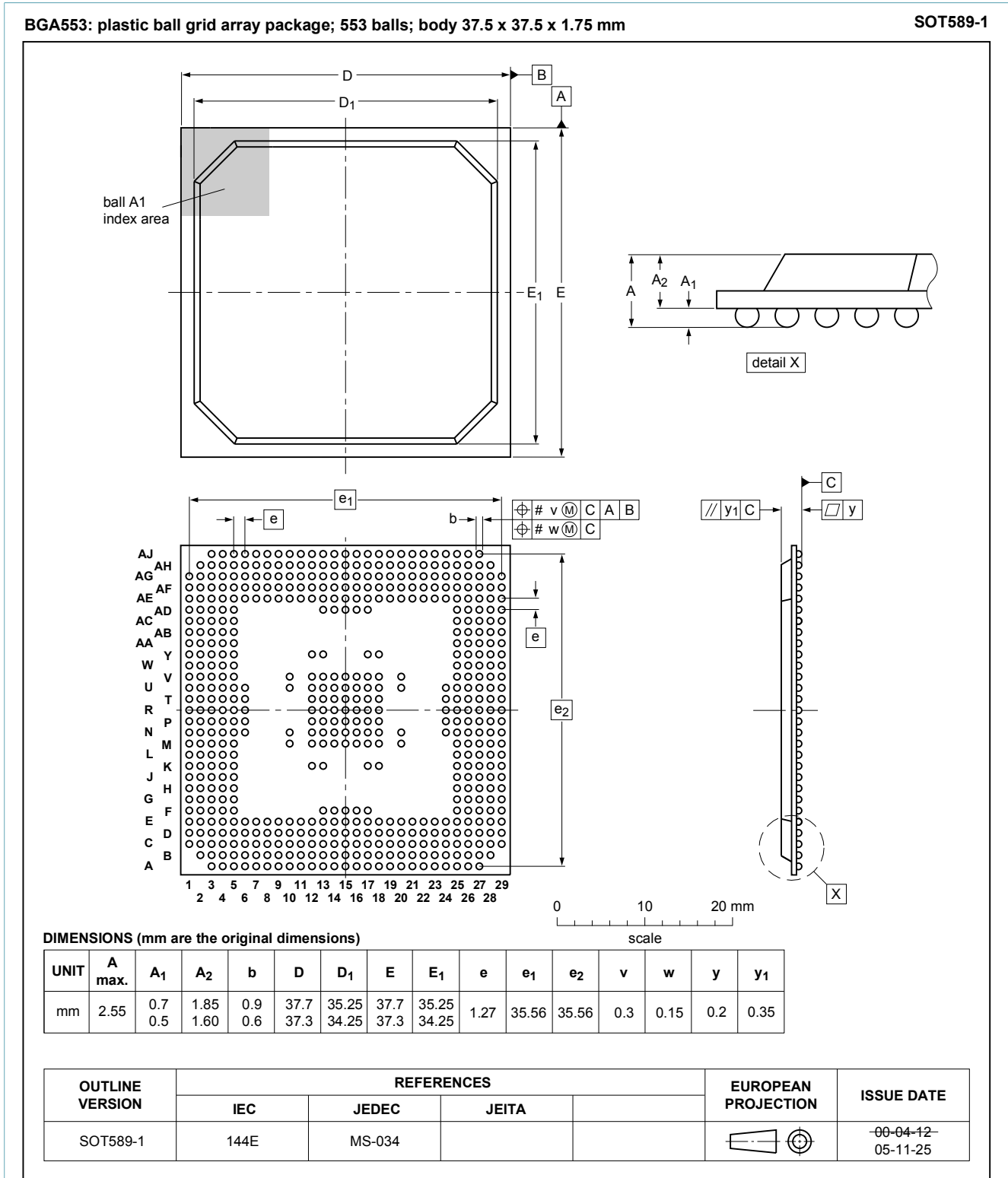
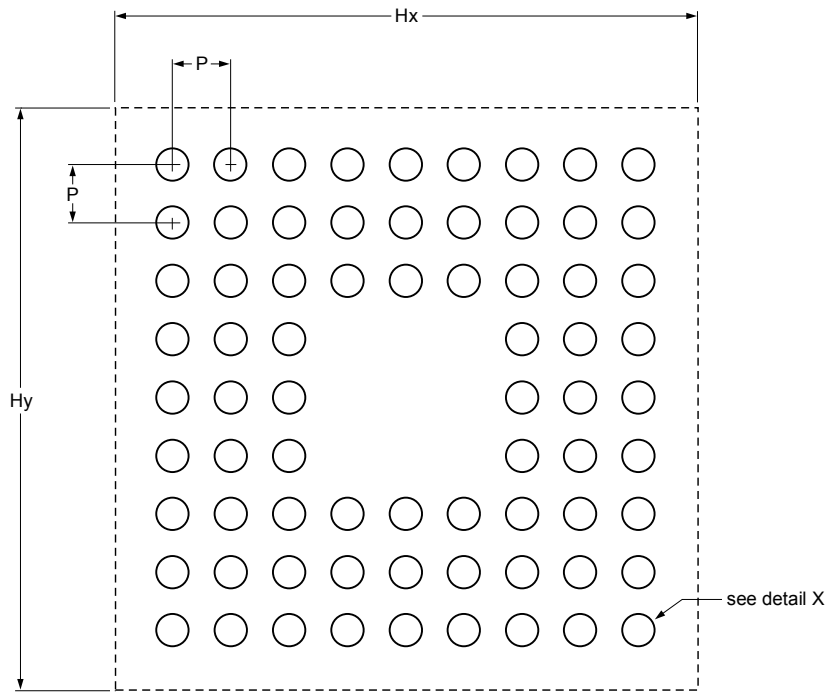


Fig. 1. Package outline BGA553 (SOT589-1)




3. Soldering

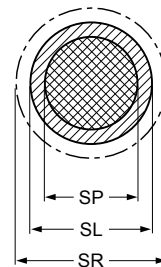
Footprint information for reflow soldering of BGA553 package

SOT589-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

Dimensions in mm

P	SL	SP	SR	Hx	Hy
1.27	0.600	0.500	0.750	38.075	38.075

sot589-1_fr

Fig. 2. Reflow soldering footprint for BGA553 (SOT589-1)

4. Legal information

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For sales office addresses, please send an email to: salesaddresses@nxp.com

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